


3N211
3N212
3N213

TO-72



DUAL-GATE
MOSFET
VHF AMPLIFIER

N-CHANNEL — DEPLETION

MAXIMUM RATINGS

Rating	Symbol	3N211 3N212	3N213	Unit
Drain-Source Voltage	V _{DS}	27	35	V _{dc}
Drain-Gate Voltage	V _{DG1} V _{DG2}	35 35	40 40	V _{dc}
Drain Current	I _D	50		mAdc
Gate Current	I _{G1} I _{G2}	± 10 ± 10		mAdc
Total Device Dissipation @ T _A = 25°C Derate above 25°C	P _D	360 2.4		mW mW/°C
Total Device Dissipation @ T _C = 25°C Derate above 25°C	P _D	1.2 8.0		Watt mW/°C
Lead Temperature, 1/16" From Seated Surface for 10 seconds	T _L	300		°C
Junction Temperature Range	T _J	- 65 to + 175		°C
Storage Temperature Range	T _{stg}	- 65 to + 175		°C

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted.)

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				
Drain-Source Breakdown Voltage (I _D = 10 μAdc, V _{G1S} = V _{G2S} = -4.0 Vdc)	V _{(BR)DSX}	25 30	—	V _{dc}
Instantaneous Drain-Source Breakdown Voltage(1) (I _D = 10 μAdc, V _{G1S} = V _{G2S} = -4.0 Vdc)	V _{(BR)DSX}	27 35	—	V _{dc}
Gate 1-Source Breakdown Voltage(2) (I _{G1} = ±10 mAdc, V _{G2S} = V _{DS} = 0)	V _{(BR)G1SO}	±6.0	—	V _{dc}
Gate 2-Source Breakdown Voltage(2) (I _{G2} = ±10 mAdc, V _{G1S} = V _{DS} = 0)	V _{(BR)G2SO}	±6.0	—	V _{dc}
Gate 1 Leakage Current (V _{G1S} = ±5.0 Vdc, V _{G2S} = V _{DS} = 0) (V _{G1S} = -5.0 Vdc, V _{G2S} = V _{DS} = 0, T _A = 150°C)	I _{G1SS}	—	±10 -10	nAdc μAdc
Gate 2 Leakage Current (V _{G2S} = ±5.0 Vdc, V _{G1S} = V _{DS} = 0) (V _{G2S} = -5.0 Vdc, V _{G1S} = V _{DS} = 0, T _A = 150°C)	I _{G2SS}	—	±10 -10	nAdc μAdc
Gate 1 to Source Cutoff Voltage (V _{DS} = 15 Vdc, V _{G2S} = 4.0 Vdc, I _D = 20 μAdc)	V _{G1S(off)}	-0.5 -0.5	-5.5 -4.0	V _{dc}
Gate 2 to Source Cutoff Voltage (V _{DS} = 15 Vdc, V _{G1S} = 0, I _D = 20 μAdc)	V _{G2S(off)}	-0.2 -0.2	-2.5 -4.0	V _{dc}
ON CHARACTERISTICS				
Zero-Gate-Voltage Drain Current(3) (V _{DS} = 15 Vdc, V _{G1S} = 0, V _{G2S} = 4.0 Vdc)	I _{DSS}	6.0	40	mAdc
SMALL-SIGNAL CHARACTERISTICS				
Forward Transfer Admittance(4) (V _{DS} = 15 Vdc, V _{G2S} = 4.0 Vdc, V _{G1S} = 0, f = 1.0 kHz)	y _{fs}	17 15	40 35	mmhos
Reverse Transfer Capacitance (V _{DS} = 15 Vdc, V _{G2S} = 4.0 Vdc, I _D = 10 mAdc, f = 1.0 MHz)	C _{rss}	0.005	0.05	pF
FUNCTIONAL CHARACTERISTICS				
Noise Figure (V _{DD} = 18 Vdc, V _{GG} = 7.0 Vdc, f = 200 MHz) (V _{DD} = 24 Vdc, V _{GG} = 6.0 Vdc, f = 45 MHz)	NF	—	3.5 4.0	dB



ELECTRICAL CHARACTERISTICS(T_A = 25°C unless otherwise noted.)

Characteristic		Symbol	Min	Max	Unit
Common Source Power Gain (V _{DD} = 18 Vdc, V _{GG} = 7.0 Vdc, f = 200 MHz) (V _{DD} = 24 Vdc, V _{GG} = 6.0 Vdc, f = 45 MHz) (V _{DD} = 24 Vdc, V _{GG} = 6.0 Vdc, f = 45 MHz) (V _{DD} = 18 Vdc, f _{LO} = 245 MHz, f _{RF} = 200 MHz)	3N211	G _{ps}	24	35	dB
	3N211		29	37	
	3N213	G _c (6)	27	35	
	3N212		21	28	
Bandwidth (V _{DD} = 18 Vdc, V _{GG} = 7.0 Vdc, f = 200 MHz) (V _{DD} = 18 Vdc, f _{LO} = 245 MHz, f _{RF} = 200 MHz) (V _{DD} = 24 Vdc, V _{GG} = 6.0 Vdc, f = 45 MHz)	3N211	BW	5.0	12	MHz
	3N212		4.0	7.0	
	3N211,213		3.5	6.0	
Gain Control Gate-Supply Voltage(5) (V _{DD} = 18 Vdc, ΔG _{ps} = -30 dB, f = 200 MHz) (V _{DD} = 24 Vdc, ΔG _{ps} = -30 dB, f = 45 MHz)	3N211	V _{GG} (GC)	—	-2.0	Vdc
	2N211,213		—	±1.0	

(1) Measured after five seconds of applied voltage.

(2) All gate breakdown voltages are measured while the device is conducting rated gate current. This ensures that the gate-voltage limiting network is functioning properly.

(3) Pulse Test: Pulse Width = 300 μs, Duty Cycle ≤ 2.0%.

(4) This parameter must be measured with bias voltages applied for less than 5 seconds to avoid overheating. The signal is applied to gate 1 with gate 2 at ac ground.

(5) ΔG_{ps} is defined as the change in G_{ps} from the value at V_{GG} = 7.0 Volts (3N211) and V_{GG} = 6.0 Volts (3N213).(6) Power Gain Conversion. Amplitude at input from local oscillator is adjusted for maximum G_c.